



Material Content Data Sheet



Sales Product Name	TLE8088EM			Issued	25. January 2018			
MA#	MA001686794							
Package	PG-SSOP-24-9			Weight*	150.37 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.412	1.60	1.60	16042	16042
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		447	
	non noble metal	iron	7439-89-6	1.345	0.89		8945	
wire	non noble metal	copper	7440-50-8	54.617	36.32	37.26	363219	372723
	non noble metal	copper	7440-50-8	0.479	0.32	0.32	3183	3183
	encapsulation	organic material	carbon black	1333-86-4	0.175	0.12		1164
encapsulation	plastics	epoxy resin	-	8.049	5.35		53529	
	inorganic material	silicondioxide	60676-86-0	79.267	52.72	58.19	527148	581841
leadfinish	non noble metal	tin	7440-31-5	2.911	1.94	1.94	19358	19358
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1558	1558
glue	plastics	epoxy resin	-	0.199	0.13		1324	
	noble metal	silver	7440-22-4	0.597	0.40	0.53	3971	5295
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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